



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
40V	20mΩ@10V	14A
	26mΩ@4.5V	
-40V	46mΩ@-10V	-14A
	75mΩ@-4.5V	

Feature

- Trench Technology Power MOSFET
- Low $R_{DS(ON)}$
- Low Gate Charge
- Low Gate Resistance

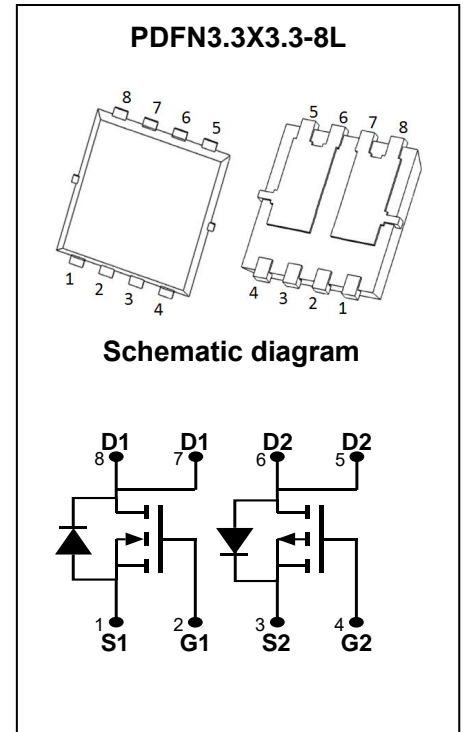
Application

- PWM Applications
- Loas Switch
- Power Management

MARKING:



M400NP04L = Device Code
 XX = Data Code
 Solid Dot = Green Device Indicator



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	NMOS	PMOS	Unit
Drain - Source Voltage	V_{DS}	40	-40	V
Gate - Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current ^{1,5}	I_D	14	-14	A
$T_C = 25^\circ\text{C}$				
Pulsed Drain Current ²	I_{DM}	56	-56	A
Single Pulsed Avalanche Current ³	I_{AS}	10	-11	A
Single Pulsed Avalanche Energy ³	E_{AS}	28	35	mJ
Power Dissipation ^{4,5}	P_D	2	3.2	W
Thermal Resistance from Junction to Case ⁵	$R_{\theta JC}$	8.8	8.8	$^\circ\text{C/W}$
Junction Temperature	T_J	150	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	-55~ +150	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

NMOS:

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	40			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V			1	μA
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics³						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	2.1	3.0	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 6.0A		20	36	mΩ
		V _{GS} = 4.5V, I _D = 6.0A		26	56	
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 20V, V _{GS} = 0V, f = 1MHz		767		pF
Output Capacitance	C _{oss}			60		
Reverse Transfer Capacitance	C _{rss}			46		
Gate Resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f = 1MHz		2.3		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = 20V, V _{GS} = 10V, I _D = 6A		15.3		pC
Gate-source Charge	Q _{gs}			2.5		
Gate-drain Charge	Q _{gd}			3.5		
Turn-on Delay Time	t _{d(on)}	V _{DD} = 20V, V _{GS} = 10V, R _L = 2.5Ω R _G = 3Ω		5		ns
Turn-on Rise Time	t _r			3		
Turn-off Delay Time	t _{d(off)}			15		
Turn-off Fall Time	t _f			2		
Source - Drain Diode Characteristics						
Diode Forward Voltage ³	V _{SD}	V _{GS} = 0V, I _S = 1.0A			1.2	V

PMOS:

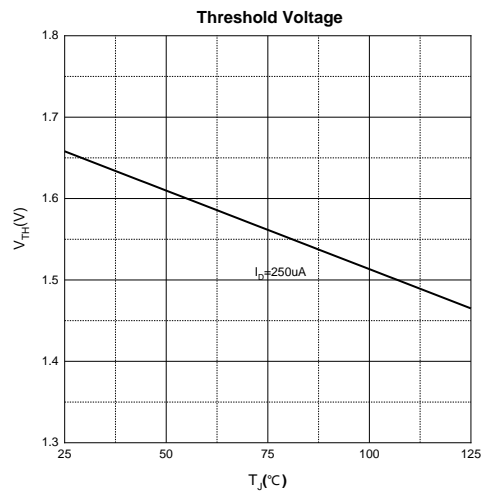
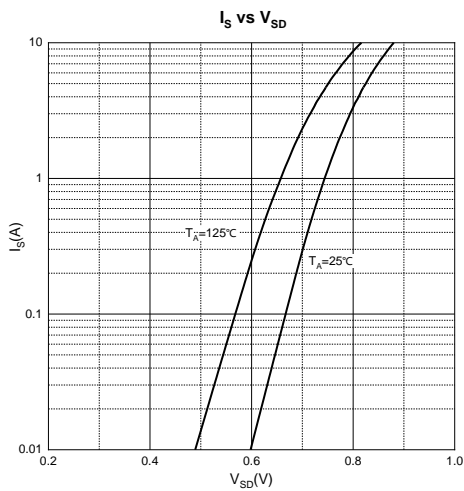
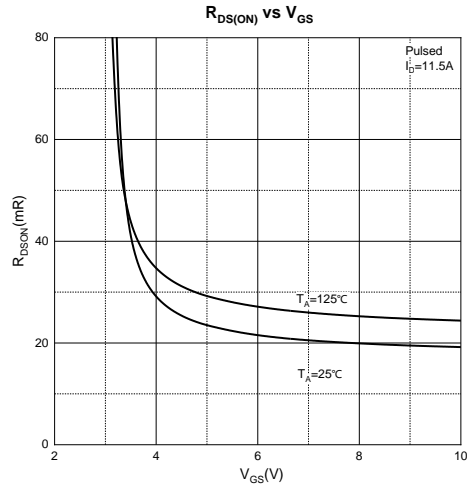
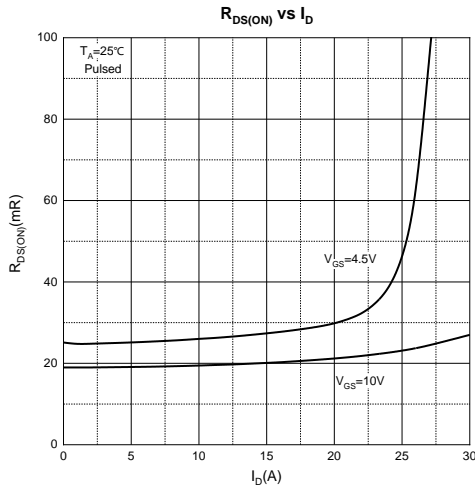
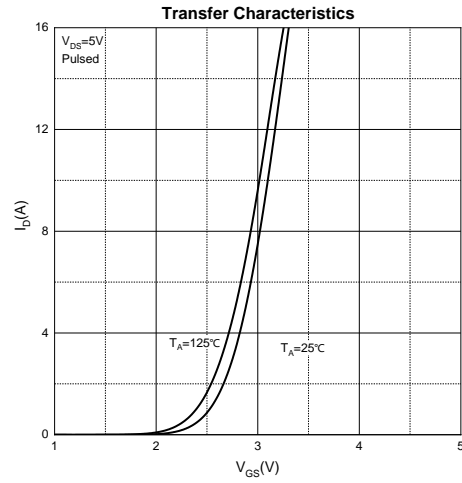
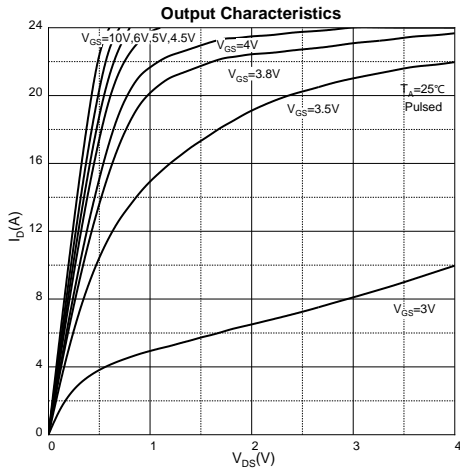
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain - Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-40			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -40V, V_{GS} = 0V$			-1	μA
Gate - Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
On Characteristics³						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.5	-3.0	V
Drain-source On-resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -5.0A$		46	60	m Ω
		$V_{GS} = -4.5V, I_D = -5.0A$		75	98	
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{DS} = -20V, V_{GS} = 0V, f = 1MHz$		677		pF
Output Capacitance	C_{oss}			70		
Reverse Transfer Capacitance	C_{rss}			53		
Gate Resistance	R_g	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$		25		Ω
Switching Characteristics						
Total Gate Charge	Q_g	$V_{DS} = -20V, V_{GS} = -10V, I_D = -5A$		13		pC
Gate-source Charge	Q_{gs}			2.5		
Gate-drain Charge	Q_{gd}			3		
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -20V, V_{GS} = -10V, R_L = 2.3\Omega$ $R_G = 6\Omega$		8		ns
Turn-on Rise Time	t_r			6		
Turn-off Delay Time	$t_{d(off)}$			20		
Turn-off Fall Time	t_f			7		
Source - Drain Diode Characteristics						
Diode Forward Voltage ³	V_{SD}	$V_{GS} = 0V, I_S = -1.0A$			-1.2	V

Notes :

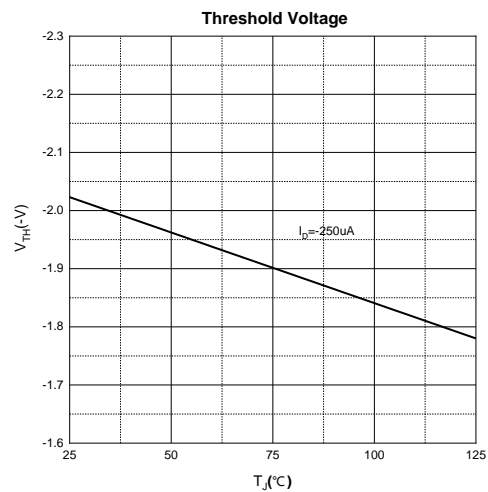
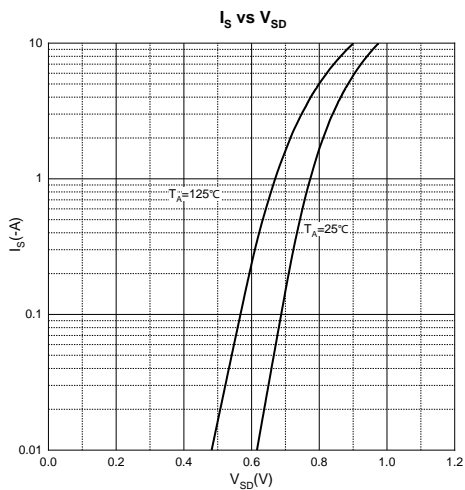
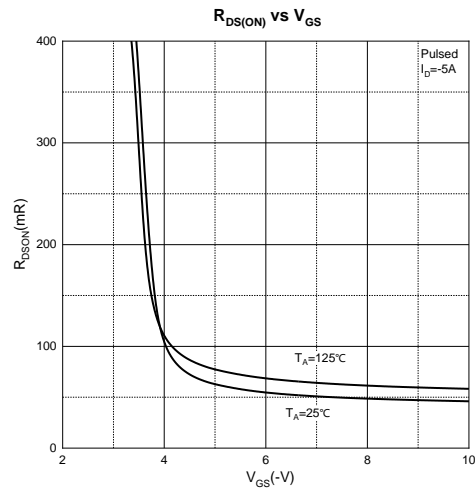
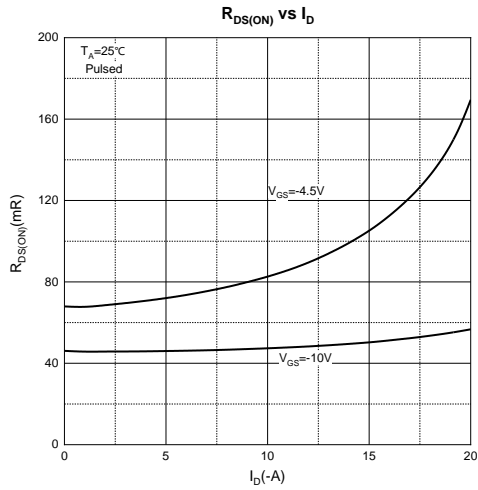
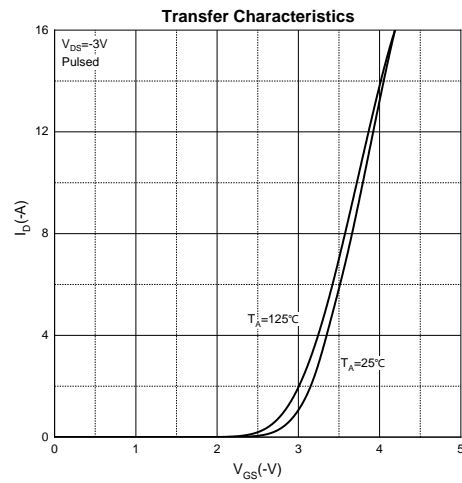
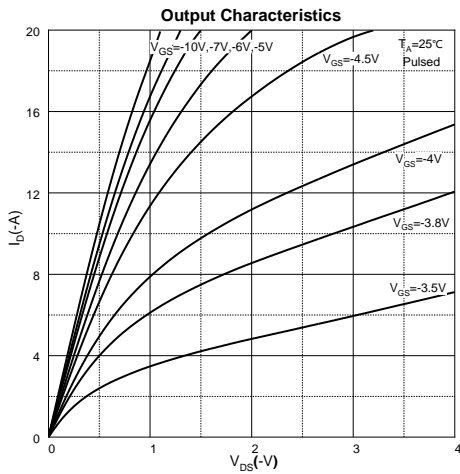
- 1.The maximum current rating is limited by package.And device mounted on a large heatsink
- 2.Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
- 3.EAS condition: $V_{DD} = 20V, V_{GS} = 10V, L = 0.5mH, R_G = 25\Omega$ Starting $T_J = 25^\circ C$.
- 4.Pulse Test : Pulse Width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 5.The power dissipation P_D is limited by $T_{J(MAX)} = 40^\circ C$.And device mounted on a large heatsink
- 6.Device mounted on $1in^2$ FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$.

Typical Characteristics

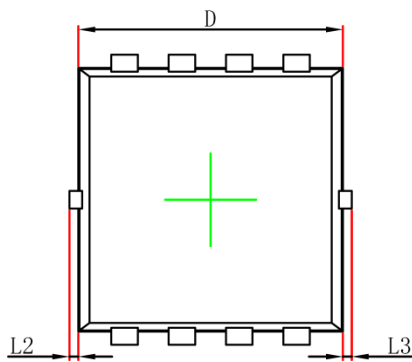
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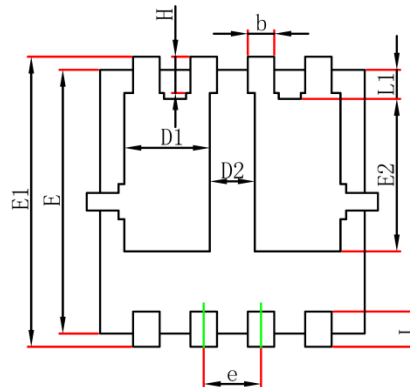
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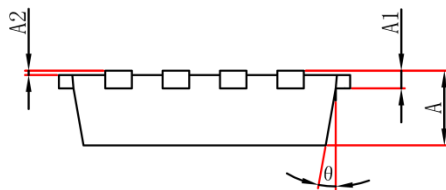
PDFN3.3X3.3-8L Package Information



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.900	0.028	0.035
A1	0.152REF		0.006REF	
A2	0.000	0.050	0.000	0.002
D	2.900	3.200	0.114	0.126
D1	0.935	1.135	0.037	0.045
D2	0.280	0.480	0.011	0.019
E	2.900	3.200	0.114	0.126
E1	3.150	3.450	0.124	0.136
E2	1.535	1.935	0.060	0.076
b	0.200	0.400	0.008	0.016
e	0.550	0.750	0.022	0.030
L	0.300	0.500	0.012	0.020
L1	0.180	0.480	0.007	0.019
L2	0.000	0.100	0.000	0.004
L3	0.000	0.100	0.000	0.004
H	0.315	0.515	0.012	0.020
θ	0°	12°	0°	12°

单击下面可查看定价，库存，交付和生命周期等信息

[>>GP\(格瑞宝\)](#)